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1. (Amended) A method of forming a microelectronic interconnect structure containing a bilayer underfill layer comprising the steps of:

- (a) forming a first polymeric material on a surface of a semiconductor wafer having interconnect pads disposed thereon;
- (b) patterning said first polymeric material to provide openings that expose said interconnect pads;
- (c) forming conductive bump material in said openings;
- (d) forming a second polymeric material that is partially cured over said first polymeric material and said conductive bump material;
- (e) dicing said semiconductor wafer into individual chips; and
- (f) bonding at least one of said individual chips to an external substrate, wherein during said bonding said conductive bump material penetrates said second polymeric material and contacts a surface of said external substrate.

#### REMARKS

Favorable reconsideration and allowance of the claims of the present application are respectfully requested.

In the present Office Action, Claim 1 is objected to because the term "undefil" needs to be changed to "underfill". In response to this formal ground of objection, applicants have amended Claim 1, line 2 to include the correct spelling of "underfill". This amendment to Claim 1 obviates the formal objection raised in the present Office Action; therefore reconsideration and withdrawal thereof are respectfully requested.

In addition to the above amendment to Claim 1, applicants have also amended Claim 1, step (d) to positively recite that a second polymeric material *that is partially cured* is